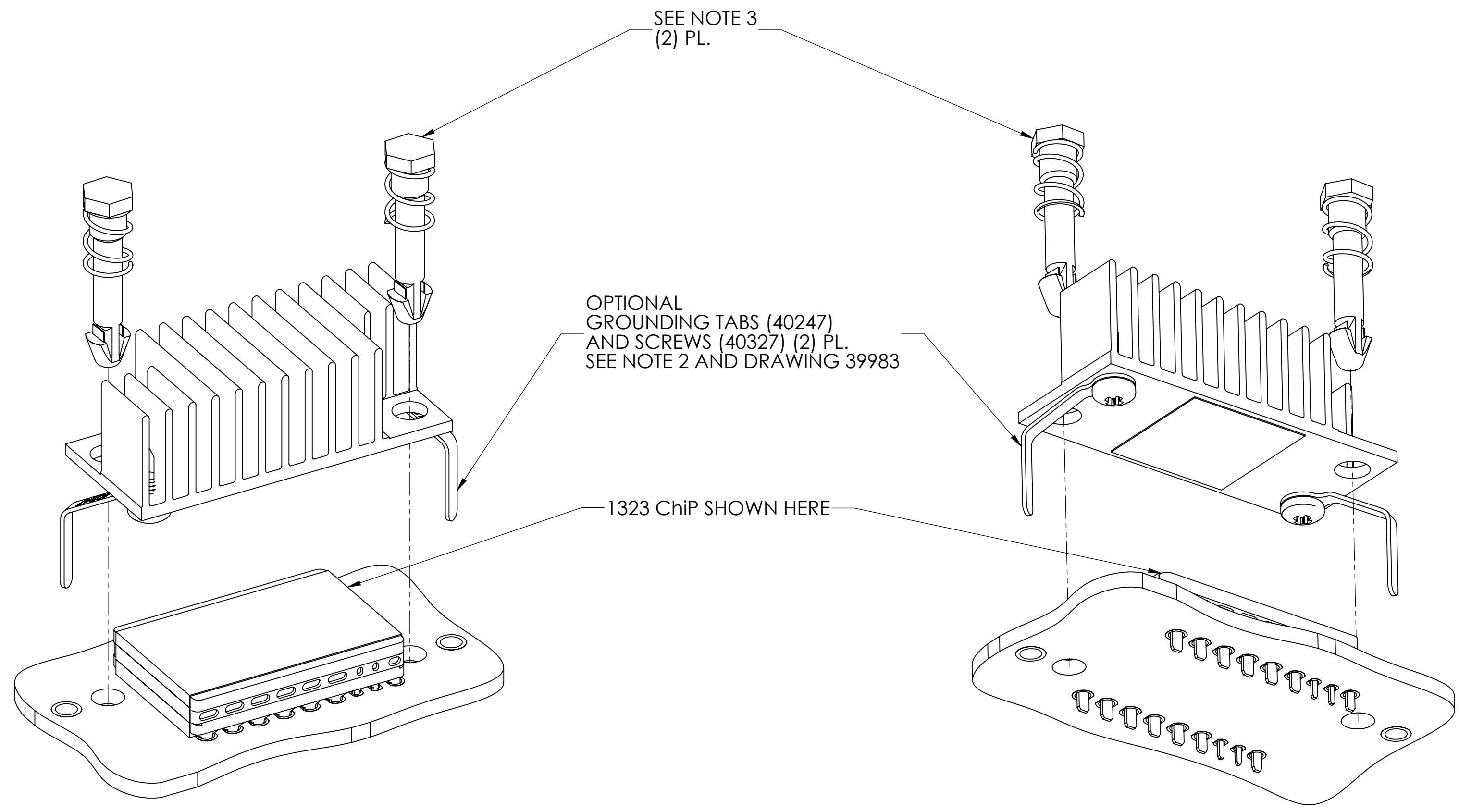
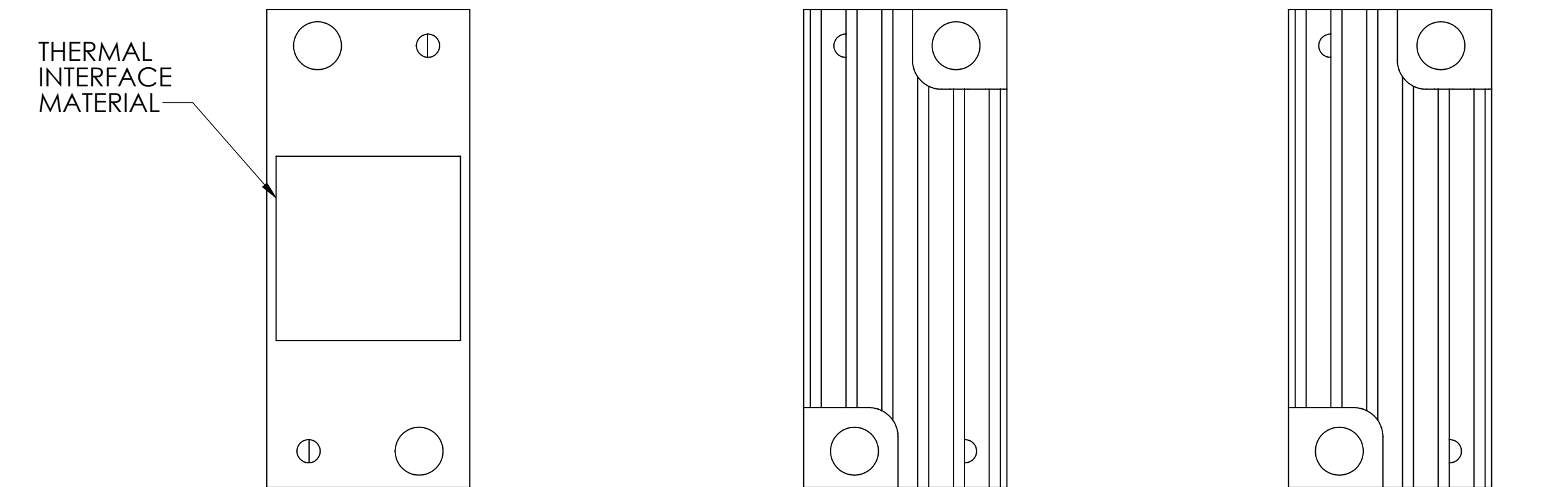
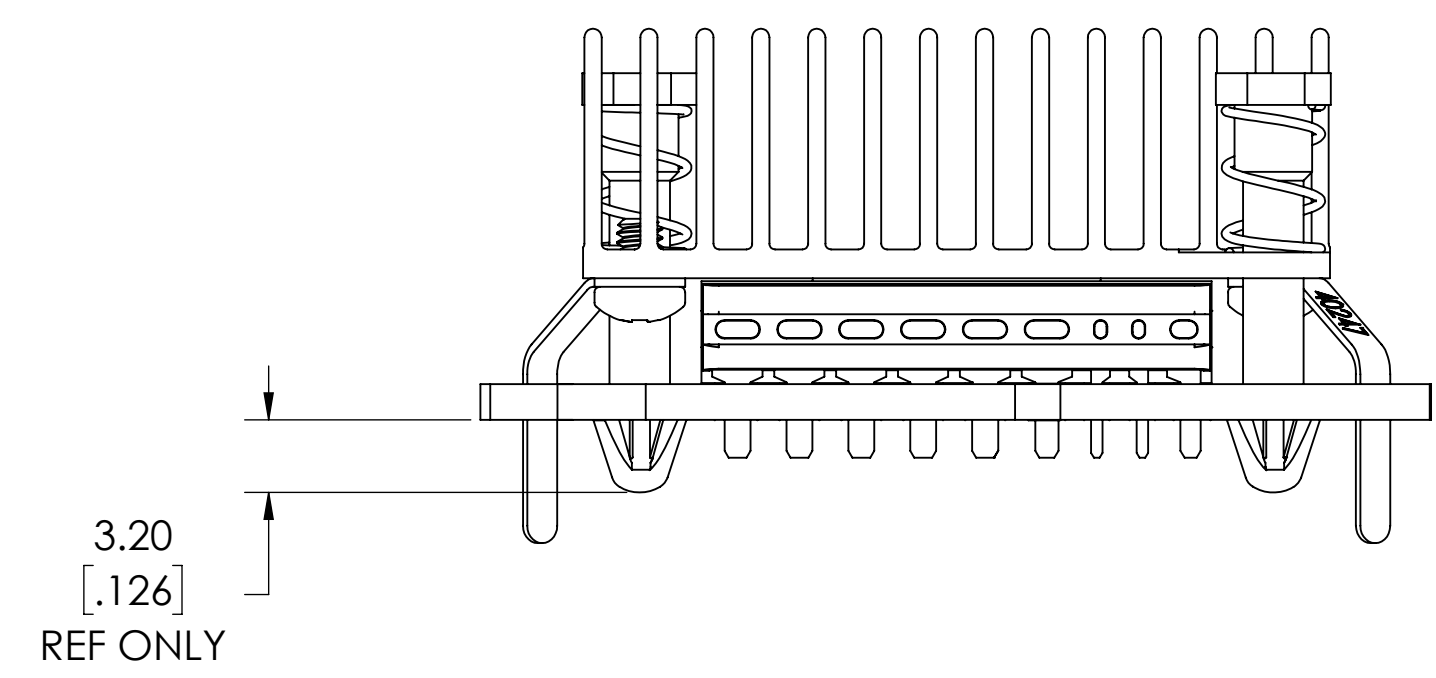


REV.	DESCRIPTION	INTL	DATE	APVD
1	RELEASED PER E140498a	SKR	04/18/14	GCK
2	REVISED PER E200529	DKT	10/19/20	RLT



ISO ASSY REF ONLY

ISO ASSY REF ONLY



- NOTES:
- FOR PCB LAYOUT SEE VICOR APPLICATION DRAWING 39983.
 - THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C. SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW:
(A) FOR HAND-SOLDERING ONLY.
(B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.

(A) PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS) ON PCB. WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.) HAND-SOLDER CHIP AND GROUNDING PINS.

(B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM. SO PARKER CHOMERICS GEL8010 IS RECOMMENDED AS A TIM. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM TO THE TOP SURFACE OF THE CHIP, OR TO THE BOTTOM SURFACE OF THE HEATSINK. PLACE CHIP ON PCB AND TOP-SIDE HEATSINK ON CHIP. WITH A CUSTOM FIXTURE APPLY APPROX. 3 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND, WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH HEATSINK AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
 - CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 1.5 LBF (6.7 N) PER PUSH-PIN.
 - RoHS COMPLIANT PER CST-0001 LATEST REVISION.

PUSH-PIN SELECTION

PUSH-PINS W/ SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
40548	WHITE	1.143 MM TO 1.626 MM [.045"] TO [.064"]	1.016 MM [.040"]	1.803 MM [.071"]
40549	BLACK	1.651 MM TO 2.464 MM [.065"] TO [.097"]	1.499 MM [.059"]	2.743 MM [.108"]
40550	BLUE	2.489 MM TO 3.150 MM [.098"] TO [.124"]	2.235 MM [.088"]	3.505 MM [.138"]
40551	GRAY	3.175 MM TO 3.708 MM [.125"] TO [.146"]	2.870 MM [.113"]	4.115 MM [.162"]

HEATSINK SELECTION

CHIP SIZE	HEAT SINK TYPE	P/N HEATSINK ONLY	P/N HEATSINK W/ TIM ONLY	P/N HEATSINK, TIM, AND GROUND TAB	P/N HEATSINK W/ GROUND TAB ONLY
1323	LF 11MM	39963	40758	40756	40757
	XF 11MM	39964	40761	40759	40760

DRAWN BY Robert Wasik	DATE 09/11/2013	VICOR <small>swd</small>	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE: INCH / (MM)		APP DWG, CHIP PUSHPIN TOPSIDE HEATSINK, 1323	
TOLERANCES ARE: X.XX (X.X) = +0.01 (0.25) X.XXX (X.XX) = +0.005 (0.127)	ANGLES ±1°	SIZE D	CAGE CODE 67131
THIRD ANGLE PROJECTION 	SCALE 3:1	DWG NO 40415	REV 2
DO NOT SCALE DRAWING		SHEET 1 OF 1	